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## PLASMA DIAGNOSIS OF FACING TARGETS SPUTTERING SYSTEM FOR DEPOSITION OF BA FERRITE FILMS IN Ar, Xe AND O<sub>2</sub> GAS MIXTURE

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### ABSTRACT

The diagnosis of the plasma in the facing targets sputtering system was performed in mixture gas of Ar 0.18-0.0 Pa, Xe 0.0-0.18 Pa and O<sub>2</sub> 0.02 Pa by using Langmuir's probe and the effect of plasma-damage to surface smoothness and magnetic characteristics of Ba ferrite films was clarified. The electron density  $N_e$  and the electron temperature  $T_e$  were evaluated at the center of the plasma and at the neighborhood of the anode ring.  $T_e$  decreased and  $N_e$  increased with increase of  $P_{Xe}$  at the center of plasma. For the measurement at the neighborhood of the anode ring,  $T_e$  was almost constant and  $N_e$  took the minimum value at  $P_{Xe}$  of 0.1 Pa, where Ba ferrite films with excellent c-axis orientation and magnetic characteristics were obtained. It was suggested that the restriction of the bombardment of recoiled particles as well as the suppress of plasma-damage were effective for obtaining good surface smoothness and excellent magnetic characteristics and it was useful for decreasing the crystallization temperature of Ba ferrite films.

### INTRODUCTION

The facing targets sputtering (FTS) apparatus can achieve the deposition free from damage by  $\gamma$ -electron and high adatom mobility at substrate surface<sup>1)</sup>. However, when target was composed of atoms with large atomic weight and it was larger than that of sputtering gas such as Ar, the particles recoiled at the target surface might bombard to growing film seriously. Since it may prevent the crystallite growth and sometimes they are incorporated to the film structure, the substrate temperature  $T_s$  for obtaining good

crystallization might be increased. In the previous study, we succeeded to decrease the critical  $T_s$  for obtaining c-axis orientation of BaM ferrite from 550 to 475°C by mixing appropriate amount of Xe into sputtering gas mixture instead of Ar<sup>2)</sup>. The discharge voltage increased with the increase of the partial Xe pressure  $P_{Xe}$ , the plasma conditions might also be changed and therefore, good crystallographic and magnetic characteristics were obtained even at low  $T_s$  of 475°C at the optimized  $P_{Xe}$  of 0.1 Pa. In this study, the diagnosis of the plasma in the facing targets sputtering system in mixture gas of Ar, Xe and

O<sub>2</sub> was performed by using Langmuir's probe to clarify the effect of plasma damage to surface smoothness and crystallographic and magnetic characteristics of Ba ferrite films.

### EXPERIMENTAL PROCEDURE

The specimen BaM ferrite films were deposited on ZnO underlayer by using FTS apparatus as illustrated in Fig. 1. The discharge plasma in the apparatus can be confined in the space between two facing targets by applying the magnetic field perpendicularly to the target planes, the growing film and the substrate can avoid the exposure to discharge plasma, i.e. the bombardment of hot- $\gamma$  electrons and negative oxygen ions with high energy<sup>1)</sup>. However, the recoiled neutral particles with high energy occur at target surface and may severely bombard the substrate surface. Especially, since the atomic weight of Ar(40.0) is much smaller than that of Ba (137.3), Ar recoiled by Ba might not only bombard to growing films surface but also be incorporated into the films. Therefore, Xe with the atomic weight of 131.3 was mixed in the sputtering gas. The atomic weight of Xe is much heavier than O(16.0) and Fe(55.8),

and is not so different from that of Ba as shown in Fig. 2. Therefore, the energy of the recoiled particles are fairly decreased when Xe is used as the sputtering gas as shown in Fig. 3.

The partial Xe and Ar pressures were changed in the range of 0.18–0.00 Pa and 0.00–0.18 Pa, respectively, and the O<sub>2</sub> pressure was set at constant value of 0.02 Pa as shown in Fig. 4. Table 1 lists the various de-

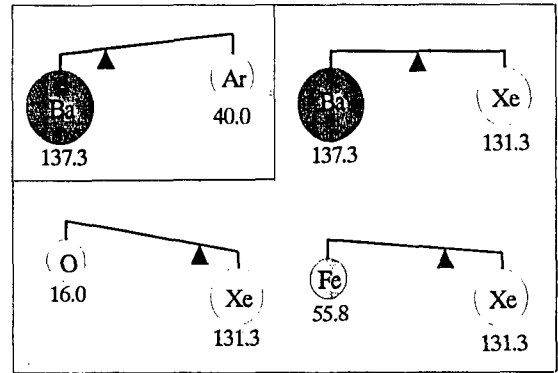


Fig. 2. Atomic weight and size of Ar, Xe, O, Ba and Fe.

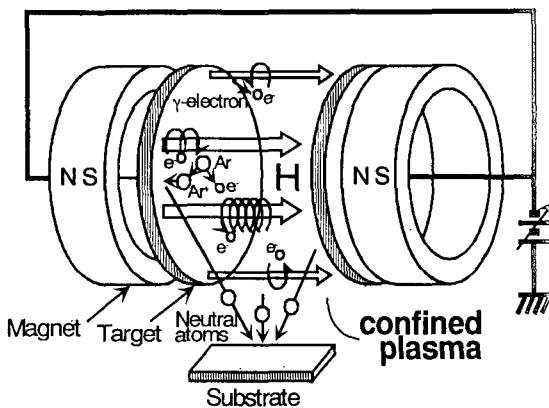


Fig. 1. Facing Targets Sputtering System.

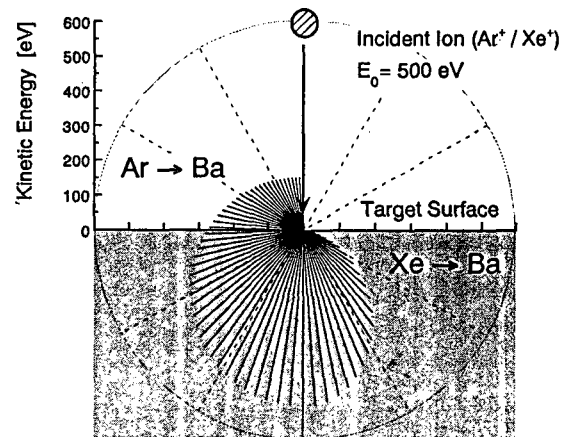


Fig. 3. Kinetic energy of recoiled Ar and Xe atoms scattered by Ba atom at target surface.

position conditions of Ba ferrite and ZnO layers. The sintered Ba ferrite plates with composition of  $\text{BaO} \cdot 6.5(\text{Fe}_2\text{O}_3)$  were used as targets and the glow discharge was sustained by using power supply at dc current of 0.1 A. The discharge voltage increased from 490 to 700 V with the increase of  $P_{Xe}$  and then the plasma became wider at higher  $P_{Xe}$ . The surface smoothness was observed and evaluated by the scanning electron microscopy (SEM) and the atomic force microscopy (AFM). The magnetic characteristics were determined by the vibrating sample magnetometer (VSM) and torque meter. The diagnosis of the plasma in mixture gas of Ar, Xe and  $\text{O}_2$  was performed by using a single type of Langmuir's probe method. The electron density  $N_e$  and the electron temperature  $T_e$  were evaluated at the center of the plasma and at the neighborhood of the anode ring.

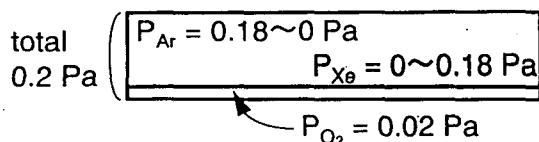


Fig. 4. Partial Ar, Xe and  $\text{O}_2$  pressures.

Table 1 : Deposition conditions for each layers.

	ZnO	BaM ferrite
target	pure Zn (4N)	$\text{BaO} \cdot 6.5\text{Fe}_2\text{O}_3$
substrate	$\text{SiO}_2/\text{Si}$	$\text{ZnO}/\text{SiO}_2/\text{Si}$
substrate temp.	300°C	600°C
film thickness	400nm	500nm
input power	70W	56~80W

## RESULTS AND DISCUSSION

Figure 5 shows the SEM images of the films deposited at  $P_{Xe}$  of (a) 0.0, (b) 0.02,

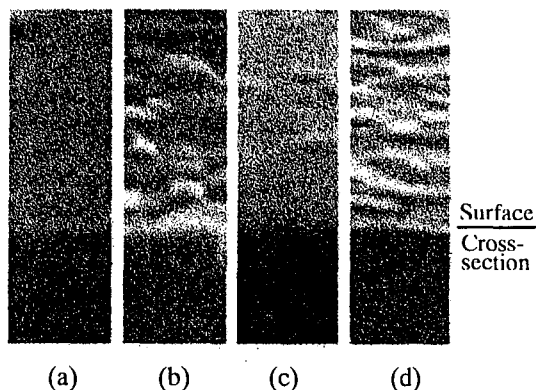


Fig. 5. SEM observations of BaM ferrite films deposited at various deposition conditions

(c) 0.10 and (d) 0.18 Pa. The center-line surface roughness evaluated by AFM was 22.0, 8.9 and 10.3 nm for (b), (c) and (d), respectively. The films revealed the best surface smoothness and possessed the best c-axis orientation in X-ray diffraction diagrams<sup>3)</sup>.

The best magnetic characteristics was also obtained at  $P_{Xe}$  of 0.1 Pa. Figure 6 shows the  $\Xi$  dependences of the saturation magnetization  $4\pi M_s$  and the perpendicular anisotropy constant  $K$  on  $P_{Xe}$ .  $4\pi M_s$  took the maximum value of 5.1 kG at  $P_{Xe}$  of 0.1 Pa. This value was larger than that of bulk BaM ferrite of 4.8 kG.  $K$  also took the maximum value of  $3.21 \times 10^5 \text{ Jm}^{-3}$  and the calculated anisotropy constant  $K_{ul}$  was  $4.23 \times 10^5 \text{ Jm}^{-3}$ . It was larger than that of bulk BaM ferrite of  $3.30 \times 10^5 \text{ Jm}^{-3}$ . It was noted that excellent surface smoothness and magnetic characteristics were obtained at the same  $P_{Xe}$  of 0.1 Pa.

Figure 7 shows the dependences of the electron density  $N_e$  and the electron temperature  $T_e$  on  $P_{Xe}$  of which the values were evaluated at the center of the plasma.  $T_e$  decreased and  $N_e$  increased with the increase of

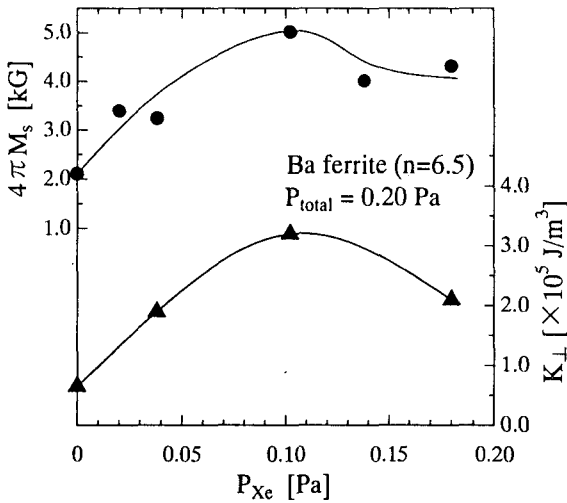


Fig. 6.  $P_{Xe}$  dependences of saturation magnetization of  $4\pi M_s$ , perpendicular and in-plane coercivities,  $H_c$  and  $H_c$ .

Figure 8 shows the  $P_{Xe}$  dependences of  $N_e$  and  $T_e$  of which the values were evaluated at the neighborhood of the anode ring. Although  $T_e$  was almost constant over the whole range of  $P_{Xe}$ ,  $N_e$  slightly decreased and took a minimum value at  $P_{Xe}$  of 0.1 Pa and increased at  $P_{Xe}$  higher than 0.1 Pa. There seemed to be many recoiled Ar and it ionized atmosphere gases in the region outside of the plasma at  $P_{Xe}$  from 0.0 to 0.04 Pa. It seemed that since the lamour radius  $rc$  equal to  $m_e v_i / eB$  of Xe ion was larger than that of Ar ion, the diameter of discharge plasma was extended to the direction perpendicular to the applied field with increase of  $P_{Xe}$  higher than 0.1 Pa. The schematic illustration of plasma exposure to substrate at various  $P_{Xe}$  were shown in Figure 9. Since the substrate surface free from plasma damage and free from recoiled particles was realized, the best surface smoothness, excellent crystallographic and magnetic characteristics were obtained at  $P_{Xe}$  of 0.1 Pa.

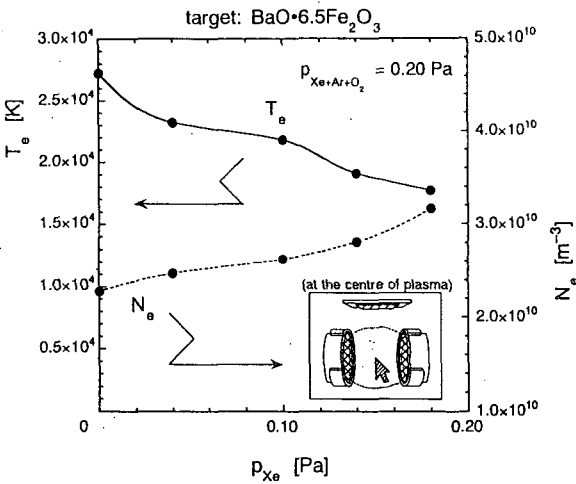


Fig. 7  $P_{Xe}$  dependences of electron density  $N_e$  and plasma temperature  $T_e$  for the measurement at the center of plasma.

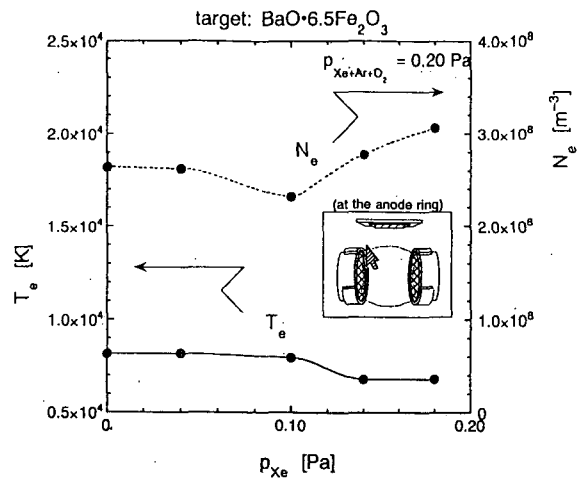


Fig. 8.  $P_{Xe}$  dependences of electron density  $N_e$  and plasma temperature  $T_e$  for the measurement at the neighborhood of anode ring.

$P_{Xe}$  and the increase of  $N_e$  seemed to be caused by the large charge transfer collision cross section of Xe. Since the  $T_e$  was gradually decreased with increase of  $P_{Xe}$ , Xe was effective to decrease the plasma temperature.

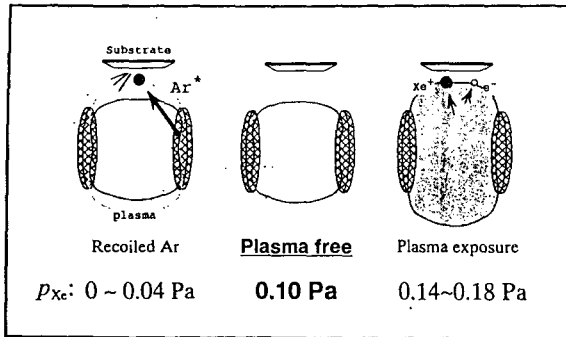


Fig. 9. Schematic illustration of situation of plasma at various  $P_{Xe}$

## CONCLUSIONS

The diagnosis of the plasma in the facing targets sputtering system was performed in mixture gas of Ar 0.18-0.0 Pa, Xe 0.0-0.18 Pa and O<sub>2</sub> 0.02 Pa by using Langmiur's probe. The electron temperature  $T_e$  decreased and the electron density  $N_e$  increased with increase of  $P_{Xe}$  at the center of plasma. For the measurement at the neighborhood of the anode ring,  $T_e$  was almost constant and  $N_e$

took the minimum value at  $P_{Xe}$  of 0.1 Pa, where Ba ferrite films with excellent surface smoothness, c-axis orientation and magnetic characteristics were obtained. It was suggested that the perfect plasma confinement and the restriction of the bombardment of recoiled particles were effective for obtaining good surface smoothness and excellent magnetic characteristics and it was useful for decreasing the crystallization temperature of Ba ferrite films.

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